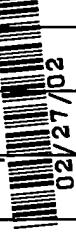
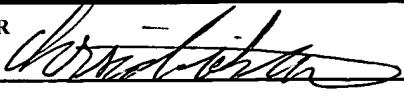


INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>				Docket Number (Optional) 03226.111001; P0259		Application Number	
				Applicant(s) Wen-Chun ZHENG et al.			
				Filing Date		Group Art Unit	
U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
 U.S. PTO 1002 U.S. 085183 10/27/02							
FOREIGN PATENT DOCUMENTS							
REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
C.C.	A1	"Thermal Performance Challenges from Silicon to Systems" (pages 1-16) published in INTEL TECHNOLOGY JOURNAL Q3, 2000 Authors: Ram Viswanath, Technology and Manufacturing Group, Intel Corp.; Vijay Wakharkar, Technology and Manufacturing Group, Intel Corp.; Abhay Watwe, Technology and Manufacturing Group, Intel Corp.; and, Vassou Lebonheur, Technology and Manufacturing Group, Intel Corp.					
EXAMINER 				DATE CONSIDERED <i>11/21/03</i>			